

L Number	Hits	Search Text	DB	Time stamp
1	2890	separat\$3 with heat\$3 with adhesive	USPAT; US-PGPUB	2003/12/18 13:47
2	99	separat\$3 with heat\$3 with adhesive with soft\$4	USPAT; US-PGPUB	2003/12/18 13:48
3	988091	@ad>19990114 or @rlad>19990114	USPAT; US-PGPUB	2003/12/18 13:48
4	74	(separat\$3 with heat\$3 with adhesive with soft\$4) not (@ad>19990114 or @rlad>19990114)	USPAT; US-PGPUB	2003/12/18 13:49
5	458164	semiconductor or "integrated circuit"	USPAT; US-PGPUB	2003/12/18 13:49
6	7	((separat\$3 with heat\$3 with adhesive with soft\$4) not (@ad>19990114 or @rlad>19990114)) and (semiconductor or "integrated circuit")	USPAT; US-PGPUB	2003/12/18 14:05